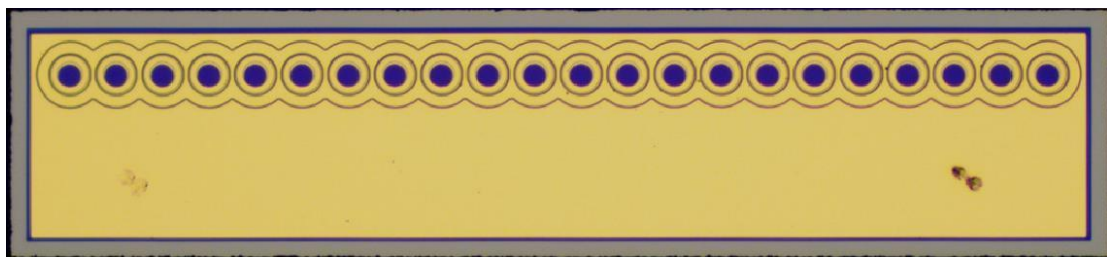


808nm 200mW VCSEL Laser Chip

Part No.: D-V0808M-0200-0836

Suitable for pulse power applications and the power is 200mW



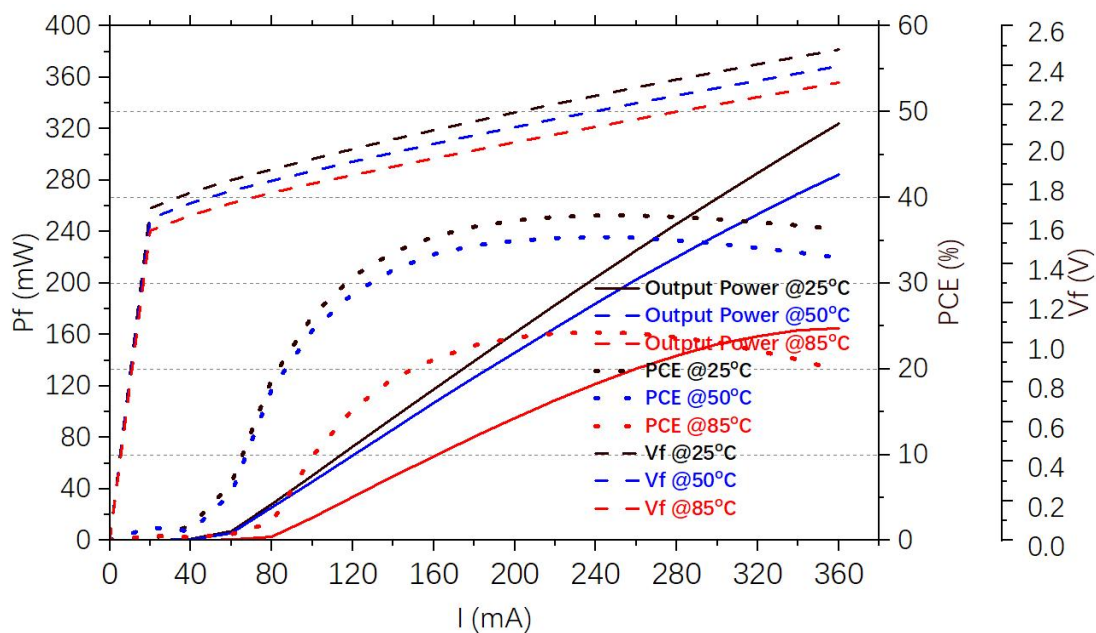
Features

- VCSEL (Vertical-Cavity Surface-Emitting Laser)
- High efficiency and reliability
- Stable central wavelength, narrow line width
- Doughnut shaped, symmetrical far field
- Surface mountable

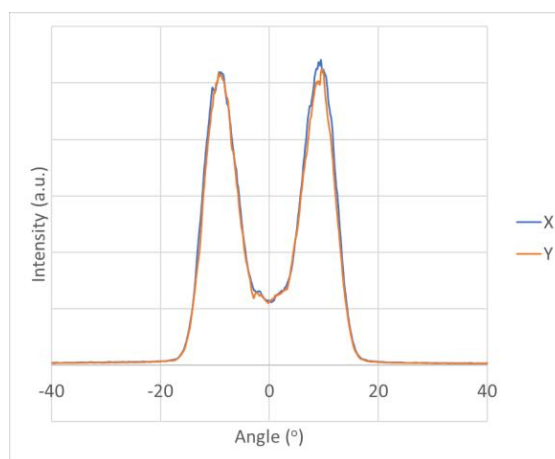
Applications

- Sensor light source
- Consumer electronic products
- Machine vision
- Red lighting

L-I-V Curve



Far Field profile



Electrical Optical Characteristics

Parameter	Symbol	Unit	Min.	Typ.	Max	Note
Threshold Current	I _{th}	mA	45	60	65	
Forward Voltage	V _F	V	2.2	2.2	2.4	IF = 280mA
Differential Resistance	R _s	Ohms	--	2	--	
Slop Efficiency	SE	W/A	1.0	1.05	1.2	
Output Power	P _{op}	mW	230	240	260	IF = 280mA
Power Conversion Efficiency	PCE	%	37	38	40	IF = 280mA
Wavelength	λ _{op}	nm	800	808	816	
Divergence Angle(1/e ²)		deg	26	28	30	IF = 280mA

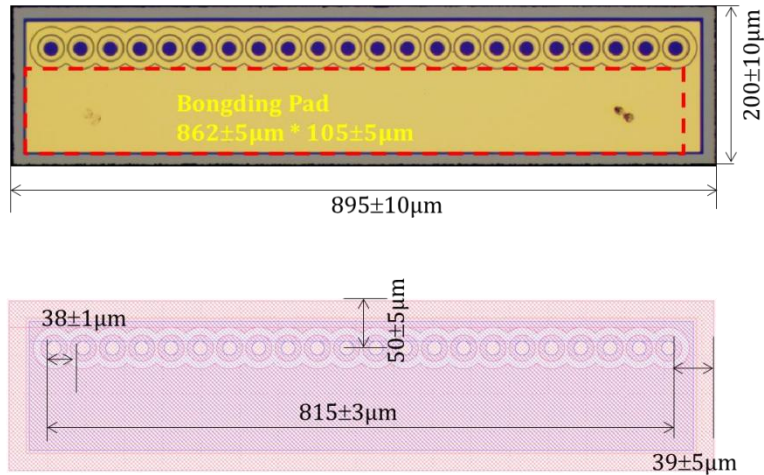
25°C, QCW Model (Pulse length 0.1ms, 10% Duty Cycle)

April 2023

The details in this document may subject to change without prior notice.

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Mechanical Specifications



参数 Parameter	规格 Specification
芯片尺寸 Die size	895±10um * 200±10um
芯片厚度 Die Thickness	130±10µm
光孔数目 Number of Emitters	22
发光点尺寸 Emitting Aperture	15±1um
焊盘尺寸 (正极) Bond Pad Size (Anode Pad)	862±5µm * 105±5µm
背面电极尺寸 (负极) Back Electrode Size (Cathode Pad)	895±10um * 200±10um

